

Multilayer Ceramic Chip Capacitors

C2012CH2A153J085AC



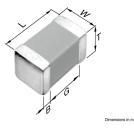






TDK item description C2012CH2A153JT****

Applications	Commercial Grade	
Feature	Mid Woltage (100 to 630V)	
Series	C2012 [EIA 0805]	
Status	Production	



Size		
Length(L)	2.00mm ±0.20mm	
Width(W)	1.25mm ±0.20mm	
Thickness(T)	0.85mm ±0.15mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.50mm Min.	
December and odd Land Dakkern (DA)	1.00mm to 1.30mm(Flow Soldering)	
Recommended Land Pattern (PA)	0.90mm to 1.20mm(Reflow Soldering)	
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)	
Neconinended Land Fattern (FB)	0.70mm to 0.90mm(Reflow Soldering)	
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)	
neconfinenced Land Fattern (FC)	0.90mm to 1.20mm(Reflow Soldering)	

Electrical Characteristics		
Capacitance	15nF ±5%	
Rated Voltage	100VDC	
Temperature Characteristic	CH(0±60ppm/°C)	
Q (Min.)	1000	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Coldoring Method	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000pcs	

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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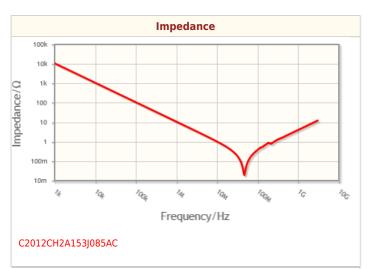


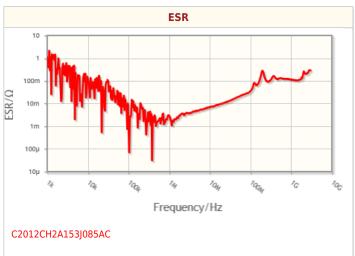


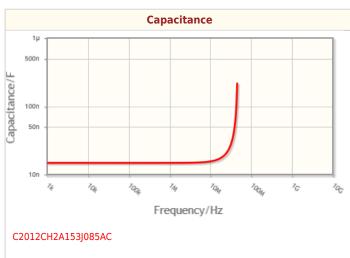


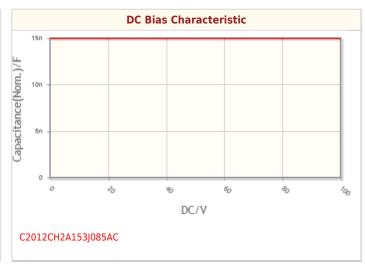


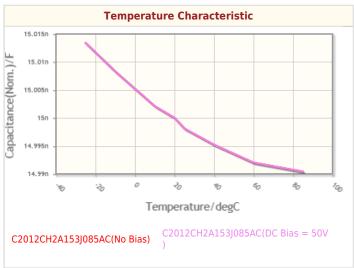
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)











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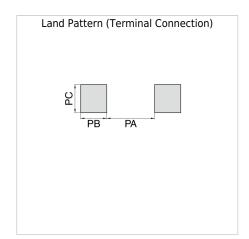








Associated Images



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